

NPN Transistor Bare Die – 2N3055

Rev 1.0 22/08/23

Bipolar Power Transistor in bare die form

Complement to PNP MJ2955

Features:

- Collector current up to 15A
- High DC Current Gain, h_{FE} = 20-70 @ I_C = 4A
- Low V_{CE(sat)} = 1.1V Max @ I_C = 4A
- Solderable back metal
- High Reliability tested grades for Military + Space

Ordering Information:

The following part suffixes apply:

- No suffix Commercial grade die
- "H" Hi-rel grade die + MIL-STD-38534 Class H LAT
- "K" Hi-rel grade die + MIL-STD-38534 Class K LAT.

LAT = Lot acceptance Test.

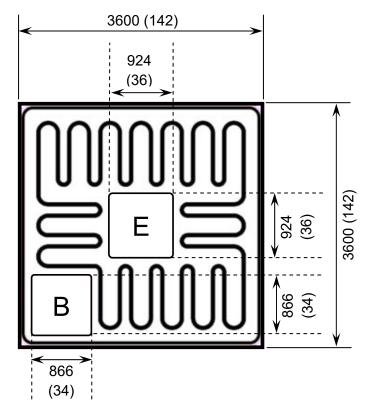
For information on Hi-Rel LAT flows please see below.

www.siliconsupplies.com\bare-die-lot-qualification

Supply Formats:

- Default Die in Waffle Pack (100 per tray capacity)
- Sawn Wafer on Tape Specific request
- Unsawn Wafer Specific request
- With additional electrical selection Specific request
- Sawn as pairs or adjacent pair pick Specific request

Die Dimensions in µm (mils)



DIE BACK = COLLECTOR

Mechanical Specification

Die Size (Excluding Saw Street)	3600 x 3600 142 x 142	µm mils	
Emitter Pad Size	924 x 924 36 x 36	μm mils	
Base Pad Size	866 x 866 34 x 34	µm mils	
Die Thickness	250 (±25) 9.84 (±1)	µm mils	
Top Metal Composition	Al		
Back Metal Composition	Ti/Ni/Ag		





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Absolute Maximum Ratings T_A = 25°C unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Collector-Base Voltage	V _{CBO}	100	V
Collector-Emitter Voltage	V _{CEO}	60	V
	V _{CER}	70	V
Emitter-Base Voltage	V _{EBO}	7	V
Collector Current - Continuous	Ic	15	Α
Base Current	I _B	7	Α
Junction Temperature	TJ	200	°C
Storage Temperature	T _{stg}	-65 to 200	°C

Electrical Characteristics T_A = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	V _{(BR)CBO}	I _E = 0	100	-	-	V
Collector-Emitter Sustaining Voltage ¹	V _{CEO(SUS)}	I _B = 0, I _C = 200mA	60	-	-	V
	V _{CER(SUS)}	$R_{BE} = 100\Omega, I_{C} = 200 \text{mA}$	70	-	-	V
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	I _C = 0	7	-	-	V
Collector Cut-off Current	I _{CEO}	V _{CE} = 30V, I _B = 0	-	-	0.7	mA
	I _{CEX}	V _{CE} = 100V, V _{BE(off)} = 1.5V	-	-	1.0	mA
	I _{CEX} ²	V _{CE} =100V,V _{BE(off)} =1.5V,T _J = 150°C	-	-	5.0	mA
Emitter Cut-off Current	I _{EBO}	V _{EB} = 7V, I _C = 0	-	-	5.0	mA
ON CHARACTERISTICS						
Forward-Current Transfer Ratio ¹	h _{FE}	$I_C = 4A$, $V_{CE} = 4V$	20	-	70	-
		I _C = 10A, V _{CE} = 4V	5	-	-	-
Collector-Emitter Saturation Voltage ¹	V _{CE(sat)}	I _C = 4A, I _B = 400mA	-	-	1.1	V
		I _C = 10A, I _B = 3.3A	-	-	3.0	V
Base-Emitter On Voltage ¹	V _{BE(on)}	$I_{C} = 4A, V_{CE} = 4V$	-	-	1.5	V
SMALL SIGNAL CHARACTERISTICS ²						
Transition Frequency ³	f _T	$V_{CE} = 10V, I_{C} = 0.5A, f_{TEST} = 1MHz$	2.5	-	-	MHz
Small-Signal Current Gain	h _{fe}	$V_{CE} = 4V, I_{C} = 1A, f = 1kHz$	15	-	120	-

^{1.} Pulsed duration = 300µs, duty cycle ≤ 2%

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^{2.} Not production testing in die form, characterized by chip design and package verification

^{3.} $f_T = |h_{fe}| \circ f_{TEST}$